

Material Content Data Sheet

RoHS

Sales Product Name	IPD127N06L G	**Issued**	24. February 2022
MA#	MA005700852		
Package	PG-TO252-3-311	**Weight***	315.77 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.28	1.28	12758	12758
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	iron	7439-89-6	0.143	0.05		454	
	non noble metal	copper	7440-50-8	143.098	45.31	45.37	453173	453763
wire	non noble metal	aluminium	7429-90-5	2.725	0.86	0.86	8630	8630
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.953	0.62		6184	
	plastics	brominated resin	-	2.092	0.66		6625	
	organic material	carbon black	1333-86-4	2.232	0.71		7067	
	plastics	epoxy resin	-	18.829	5.96		59628	
	inorganic material	silicondioxide	60676-86-0	114.366	36.22	44.17	362184	441688
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11844	11844
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	274	275
solder	non noble metal	tin	7440-31-5	0.065	0.02		205	
	noble metal	silver	7440-22-4	0.081	0.03		256	
	non noble metal	lead	7439-92-1	3.085	0.98	1.03	9770	10231
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.07	6.08	60732	60811
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com